Bluetooth low energy Wireless MCU for Automotive Applications

SimpleLink™ CC2640R2F-Q1 SimpleLink™ CC2541-Q1

Low Power RF 4Q17



Agenda

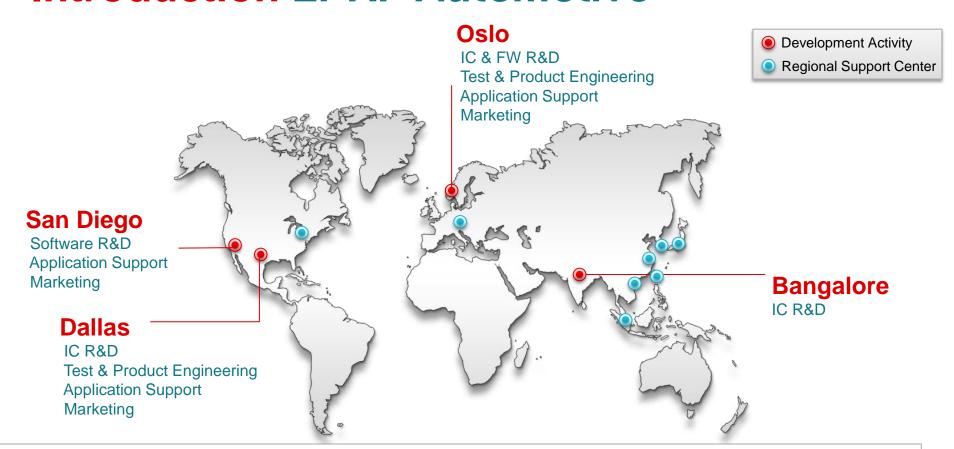
- Why BLE for Automotive?
- LPRF Automotive Introduction
- LPRF Automotive Solutions
- SimpleLink™ CC2640R2F-Q1 Wireless MCU
- Getting Started with Development

Why BLE for Automotive Applications?



- Interoperability with smartphones and wearables
- Global deployment in 2.4 GHz ISM band
- Low power for long battery life, and low footprint on car module
- Enables a cost effective solution for many emerging application

Introduction LPRF Automotive



LPRF Automotive Solutions

Overview



CC2541-Q1 Automotive Wireless MCU

Features and Benefits

- · AEC-Q100 automotive qualified
- Wireless MCU— BLE radio, MCU and embedded flash. First automotive BLE SoC with in-system programmable flash
- Grade 2 Temperature Rating (-40°C to +105°C)
- <20 mA peak current / 500 nA sleep current Long battery lifetime.
 Low average current allows for operation when the vehicle is not running
- 94 dB link budget Long Range and reliable data exchange

Software and Tools

- Royalty free BLE-STACK
- SmartRF[™] Studio and SmartRF[™] Flash Programmer
- iOS and Android sample apps
- · Extensive library of SW examples and sample code

Hardware Development Kits

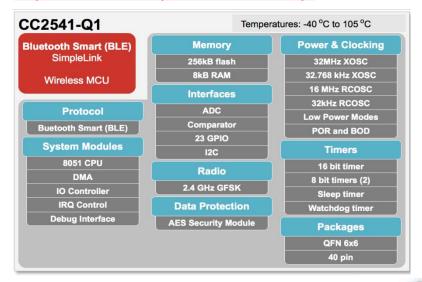




CC2541 Mini Development Kit

CC2541 Development Kit

http://www.ti.com/product/cc2541-q1



Example Applications

- · Car Access (RKE, PKE, PEPS)
- Car sharing
- Piloted parking
- Cable replacement and remote control

- Proximity sensing
- Interior lighting control
- Wireless On-Board Diagnostics
- Power seats with memory



CC2640R2F-Q1 Automotive Wireless MCU

Features and Benefits

- · AEC-Q100 automotive qualified
- Most integrated wireless MCU Design versatility and single-chip SoC
- Lowest power consumption ~6mA radio RX/TX and low sleep current for increased battery life
- Longest range 102 dB link budget for increased range and reliability
- Grade 2 Temperature Rating (-40°C to +105°C) Use in areas where elevated temperatures are common
- Wettable flanks package Enables faster and lower cost production line inspection

Software and Tools

- Software Development Kit, including royalty free Stack
- BT v4.2 support with qualified Adopted Profiles (BLE 3.x)
- SmartRF Studio & TI iOS/Android Multitool
- Sensor Controller Studio

Hardware Development Kits

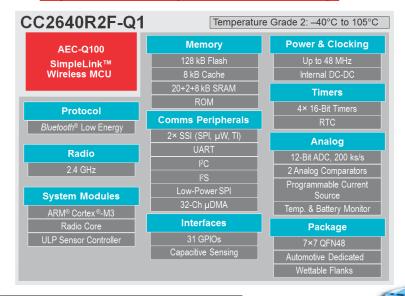




CC2650 SensorTag

CC2640R2F LaunchPad

http://www.ti.com/product/cc2640r2f-q1



Example Applications

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CC2640R2F-Q1 & CC2541-Q1 Feature Summary

Parameter	CC2640R2F-Q1	CC2541-Q1
Temperature range	-40°C to 105°C (grade 2)	-40°C to 105°C (grade 2)
Bluetooth Specification	Bluetooth v4.2 + v5.0	Bluetooth v4.0
SW Upgradeable for Future BLE Spec Updates	Yes	No
Supply Voltage Range	1.8 – 3.8 V	2.0 – 3.6 V
Current Consumption @ best RX sensitivity Current Consumption @ 0 dBm TX output power	6.2 mA 6.9 mA	18.3 mA 18.6 mA
Operating System	Yes, TI-RTOS	No, Task Scheduler
On-chip DC-DC	Yes	No
Shutdown current	150 nA	500 nA
Standby current with memory retention	1 μΑ	1 μΑ
MCU	32-bit ARM Cortex-M3 (48 MHz)	8-bit 8051 (32 MHz)
Embedded Flash / RAM	128 KB + 8 KB cache / 20 KB + On Chip ROM	256 KB / 8 KB
Output Power	+5 dBm	0 dBm
Receiver Sensitivity	-97 dBm	-94 dBm
RF Link Budget	102 dB	94 dB
Package	Automotive Grade RGZ QFN48-7x7 w/ 0.5 mm pitch	RHA QFN40-6x6 w/ 0.5 mm pitch
Wettable Flanks on QFN	Yes	No
Simultaneous Connections	Up to 8 (Multi-Role)	Up to 3 (Central to Peripheral)
#GPIOs	31	23
Development Environment	TI Code Composer Studio, IAR	IAR
Availability	Available now 15 September 2017	Available now (released April 2014)



End Equipment's for BLE

Target EE's for Bluetooth Low Energy in Automotive

Target End Equipment for BLE







Infotainment & Cluster

- Head Unit
- Telematics
- Media Interface
- Rear Seat Entertainment

BCM/Gateway

- Body Control Module (BCM)
- Junction Box
- Gateway

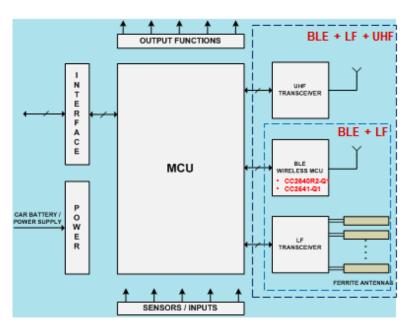
Security Systems

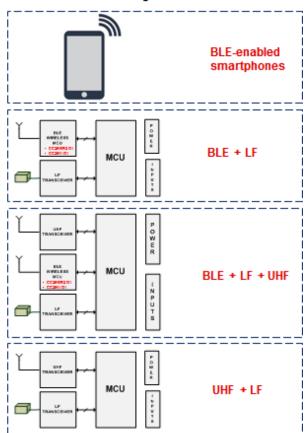
- Passive Entry Passive Start -PEPS
- Remote Keyless Entry- RKE
- Base Station

Generic Wireless Car Access

'Key Fob'

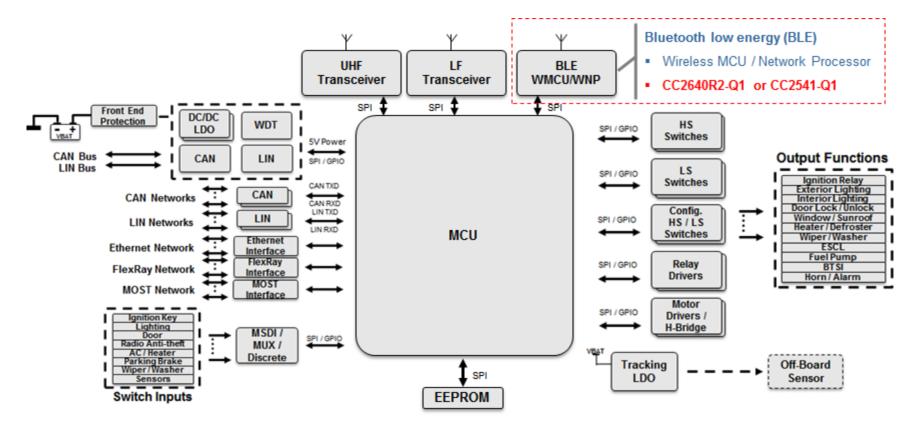
VEHICLE



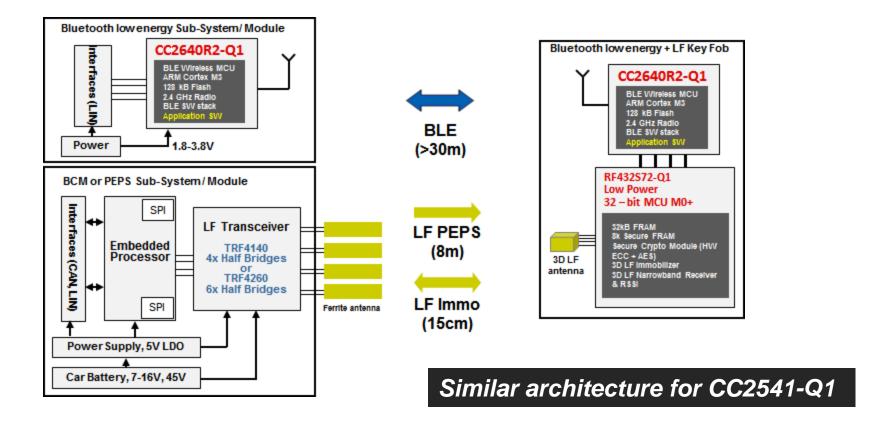


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Multifunction BCM with Gateway (Example)



BLE + LF Car Access System Block Diagram

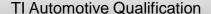


CC2640R2F-Q1

Overview, Roadmap, Schedule and Development Path



CC2640R2F-Q1 Benefits



- Wettable flanks package for enhanced production line inspection
- AEC-Q100 qualification and TI high quality automotive flow
- Grade 2 temperature range (-40C to 105C) for increase reliability
- Safe launch with TI Quality alignment

Low Power, Longest Range

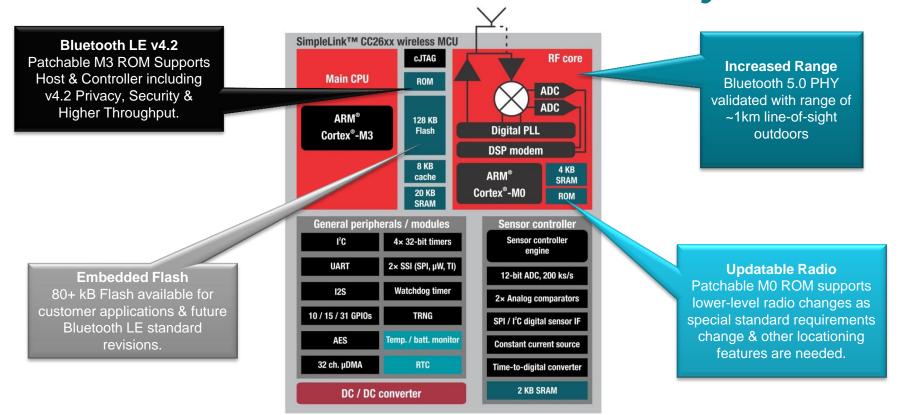
- Longest range (RX sensitivity and TX power) with superior 101dB link budget
- Lowest active and sleep power consumption for increased battery life
 - ~6 mA Radio peaks
 - 1 uA Sleep
 - 65 μA/MHz ARM Cortex M3
 - <10 uA avg. Current @ 1s CI

Platform Flexibility

- Multi-core SoC with separate application and radio domain enabling flexibility for innovation
- Bluetooth 5 qualified



CC2640R2F-Q1 Platform Flexibility



TI and AEC-Q100

 AEC Q100 is an industry standard specification developed by major automotive manufacturers and suppliers that details a set of stress tests, defines the minimum stress test driven qualification requirements, and references test conditions for the qualification of integrated circuits.

TI is actively participating in the AEC-Q100 standard process.

- TI has in-house expertise and equipment to perform stress tests (AEC-Q100 and beyond)
 - Advantages: Reliability, flexibility and quick turn-around time

TI CC2640R2F-Q1 Auto Qual beyond AEC-Q100

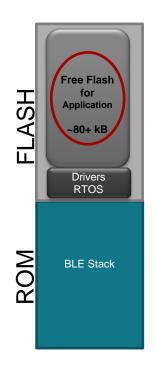
Item	AEC-Q100 Requirement	CC2640R2F-Q1 TI Qual
AEC-Q100 Defined Tests Accelerated Environment Stress Tests (THB, UHST, TC, PTC, HSTL) Accelerated Lifetime Simulation Tests (HTOL, ELFR, EDR) Package Assembly Integrity Tests (WBS, WBP, SD, PD) Electrical Verification (HBM, CDM, LU, ED)	•	>
TS-16949 certified (TI is TS-16949 compliant) TS 16949 defines the quality management system requirements for the design and development, production and, when relevant, installation and service of automotive-related products.	no	>
 Special automotive process with increased inspection and screening Statistical process control → Tighter performance parameter control → Increased device quality 		*
Automotive dedicated package with wettable flanks	no	~
Tri-temp device test (-40C/ambient/+105 C) All parts are production tested at minimum, ambient and maximum operational temperatures for increased reliability.		*
Extended documentation and support (PPAP)	no	~

CC2640R2F-Q1 vs. CC2640R2F

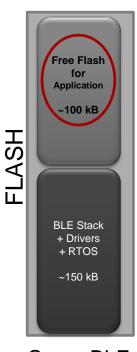
Item	Automotive CC2640R2F-Q1	Commercial CC2640R2F
Quality System	TS 16949	ISO 9001
Qualification	AEC-Q100	JEDEC
Temperature Range	-40 C to +105 C	-40 C to +85 C
Automotive qualified Fabs/AT-sites Special automotive process with increased inspection and screening (tighter performance parameter control)	Yes	No
Package	Automotive grade package with wettable flanks	Standard QFN package
Test coverage	Improved test coverage compared to CC2640R2F	Good
PCN period for significant changes	180 days	90 days
PPAP	Yes	No
Customer Return	Automotive Flow (8D)	Commercial

TI's Bluetooth low energy HW CC2640 BT4.2 Cortex M3 128KB Flash 20KB RAM Ultra low power 4x4 / 5x5 / 7x7 QFN CC2640R2F-Q1 BT5 CC2640R2F Cortex M3 CC2650MOD Cortex M3 BT4.2 Automotive qualified 275KB NV Memory **Q1** AEC-Q100 Upto 28KB RAM Pre-certified BLE module 7x7 QFN Wettable Flanks Integrated antenna Ultra low power Longest range at 2.7x2.7 WCSP lowest power 4x4 / 5x5 / 7x7 QFN CC2541-Q1 BT4.0 World's first Q1 CC2540 BT4.0 Integrated Flash Automotive qualified High output power +4dBm BLE SoC CC2541 BT4.0 Up to 256KB Flash **USB** interface Up to 256KB Flash Flexible CC2540T BT4.0 System cost optimized World's only 125C graded SimpleLink MCU Platform BLE solution 2018 2017 2019 **TEXAS INSTRUMENTS** 20

CC2640R2F-Q1 Re-Purposed Industrial CC2640R2F



TI CC2640R2F-Q1



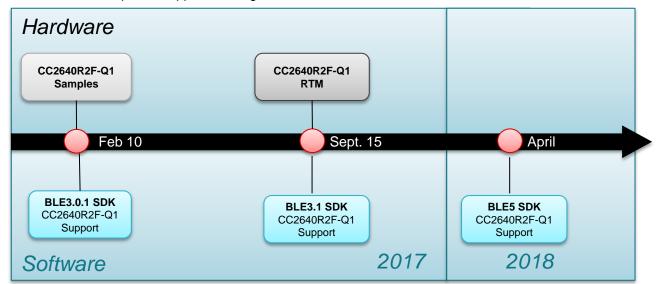
Comp BLE (256k flash)

Start Development Today

- CC2640R2F-Q1 Sampling
- ➤ 256kB flash equivalent BLE SoC
 - 80+ kB free flash for application
- ➤ Bluetooth 4.2 support in the ROM
- Bluetooth LE stack upgradable via ROM patches

CC2640R2F-Q1 Development Path

- CC2640R2F silicon and software available today
- CC2640R2F-Q1 silicon sampling
- CC2640R2F to CC2640R2F-Q1 transition
 - Pin-out and package layout compatible
 - API Compatible; Application Migration Guide Included"



Getting Started

CC2640RF2-Q1 Development



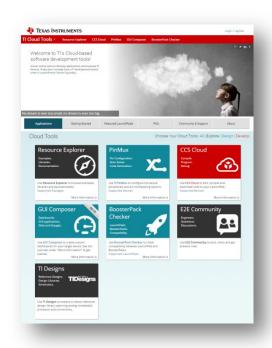
Get started right now

Use CC2640R2F for development, visit dev.ti.com



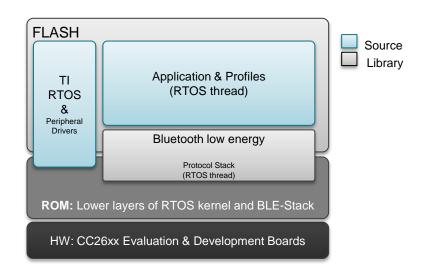
CC2640R2 Lauchpad \$29

- The LaunchPad features on-board emulation with the XDS-110 emulator, which means you can program and Debug without any additional tools
- Plenty of software examples to get started
- Comprehensive selection of add-on boards for flexible prototyping"
- Supported by accompanying iOS/Android apps



Software Platform

- BLE-Stack™ 3.0 Available now
- BT4.2 Support
 - LE Data Length Extension (2.5x Increased throughput)
 - LE Secure Connections (DH ECC)
 - LE Privacy 1.2



Getting Started with CC2640 SW Development

CCS Cloud + Project Zero

- No software needed. Only a Launchpad and a browser
- Click a button to flash device with Project Zero and follow instructions for your first iOS / Android interaction with BLE
- Import project to cloud editor and develop / build / debug, or:
- Download all needed project files in one archive file for CCS Desktop development
- Visit <u>dev.ti.com</u>

SimpleLink Academy

- Training modules integrated with CCS
- Explanations and theory
- Interactive quizzes
- Tasks with step by step instructions
- Learn about:
 - TI-RTOS concepts (Task, Semaphore etc)
 - BLE Services
 - Simple Network Processor
 - Sensor Controller Studio
 - BLE Security
 - Over the Air Download Bluetooth Developer Studio
- Visit <u>www.ti.com/ble-wiki</u>

Simple

Advanced

BLE-Stack SDK + GitHub

- Example usage of adopted profiles included in the BLE SDK installer
 - Blood Pressure
 - HID Keyboard / Mouse
 - Heart Rate
 - Cycling / Running Sensor
 - Glucose Sensor / Collector
 - .. and more
 - Visit <u>www.ti.com/ble-stack</u>
- Advanced / specialized examples
 - Simple Network Processor
 - Log application events to UART
 - Simultaneous Master/Slave
 - Visit <u>github.com/ti-simplelink</u>

Development *Tools*

SmartRF™ Tools

- SmartRF Studio
 - Radio performance evaluation, testing and configuration
- SmartRF Packet Sniffer
 - Capture over the air packets for RF link debugging and protocol analysis
- SmartRF Flash Programmer
 - Flash tool. Comes in command-line version for automated programming sequences.

Sensor Controller Studio

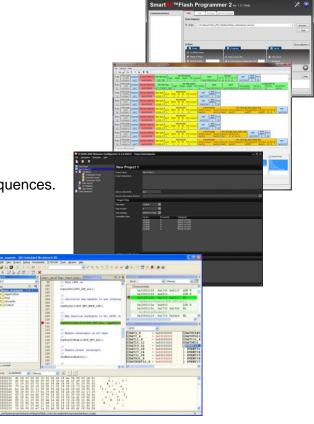
- Setup SCE tasks and code the behaviour script for them
- Generate driver source files for the CM3

Multiple software development tools supported

- IAR Embedded Workbench® for ARM
- Code Composer Studio







Evaluation *Tools*

BTool

Run and test all possible *Bluetooth* low energy functionality controlled from the PC tool.

BLE Device Monitor

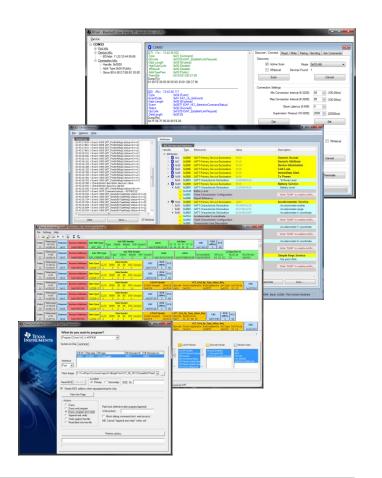
Provides an intuitive and graphical way to explore *Bluetooth* low energy Services and Characteristics.

SmartRF™ Protocol Packet Sniffer

Capture Bluetooth low energy communication live with full overview.

SmartRF™ Flash Programmer

Program devices and Read/write IEEE addresses



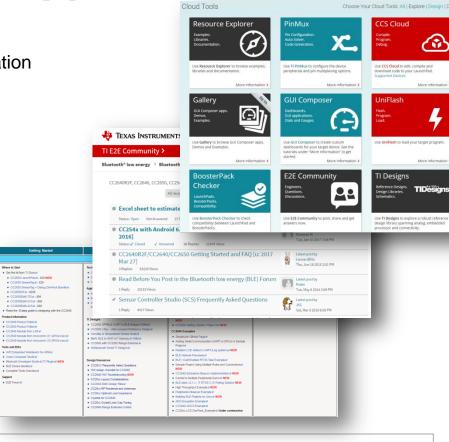
Bluetooth low energy Support Collateral

CC2950EMK-7ID # - \$99

Tools and IDEs

Complete Tools Overview

- TI Cloud Tools (dev.ti.com)
 - Resource Explorer with SDK, SLA, Documentation
 - CCS Cloud
 - And more
- E2E Support Community (www.ti.com/ble-forum)
 - Support by TI Software and Hardware experts
- GitHub SW Repository (github.com/ti-simplelink)
 - Additional SW examples to the SDK
- BLE Wiki (www.ti.com/ble-wiki)
 - Additional design resources



TEXAS INSTRUMENTS

本資料僅供參考,使用本資料需遵守TI的使用條款,詳情請參考www.ti.com.tw